

# SOT1151-1

plastic thermal enhanced ball grid array package; 640 balls;  
heatsink

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HBGA640
<b>Package type industry code</b>	HBGA640
<b>Package style descriptive code</b>	HBGA (thermal enhanced ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-034D compliant
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	19-10-2009

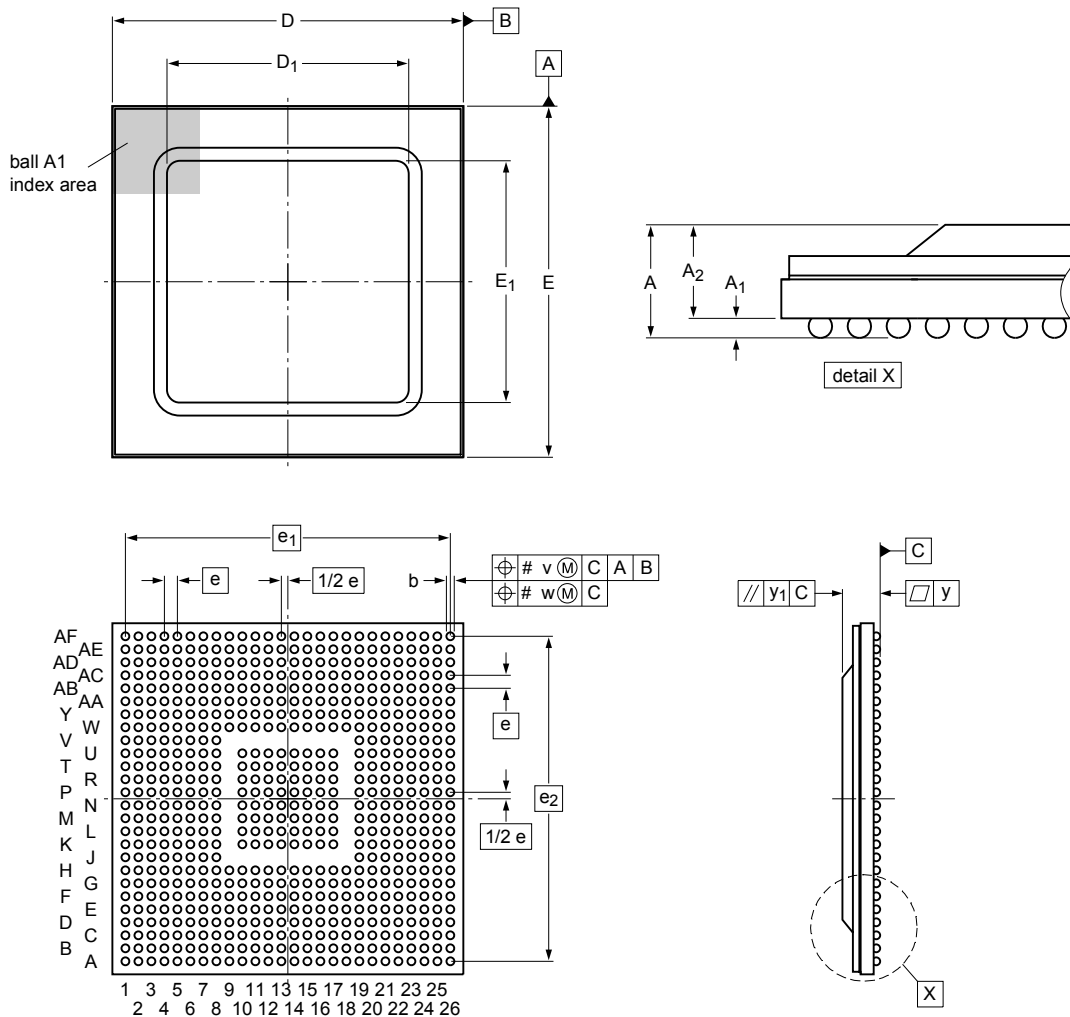
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	26.8	-	27	27.2	mm
E	package width	26.8	-	27	27.2	mm
A	seated height	2.55	-	2.9	3.25	mm
A <sub>2</sub>	package height	2.15	-	2.4	2.65	mm
e	nominal pitch	-	-	1	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	640	-	



## 2. Package outline

HBGA640: plastic thermal enhanced ball grid array package; 640 balls; heatsink SOT1151-1



Dimensions

Unit	A	A <sub>1</sub>	A <sub>2</sub>	b	D	D <sub>1</sub>	E	E <sub>1</sub>	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
max	3.25	0.6	2.65	0.65	27.2	18.65	27.2	18.65							
mm nom	2.90	0.5	2.40	0.60	27.0	18.60	27.0	18.60	1	25	25	0.25	0.1	0.15	0.3
min	2.55	0.4	2.15	0.55	26.8	18.55	26.8	18.55							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1151-1	MS-034D compliant				09-10-19

Fig. 1. Package outline HBGA640 (SOT1151-1)

### 3. Legal information

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